

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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GaAs INTEGRATED CIRCUIT $\mu PG2310TK$

GaAs MMIC LOW NOISE AMPLIFIER FOR SATELLITE RADIO

DESCRIPTION

The μ PG2310TK is a GaAs MMIC LNA for SDARS (<u>Satellite Digital Audio Radio Services</u>). High Gain and Low Distortion suit to driver stage amplifier for Satellite Radio Antenna.

FEATURES

High gain : GP = 27.0 dB TYP.
 Low distortion : OIP3 = +28.5 dBm TYP.
 6-pin lead-less minimold package (1.5 × 1.1 × 0.55 mm)

APPLICATION

Satellite Radio Antenna etc.

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPG2310TK-E2	μPG2310TK-E2-A	6-pin lead-less minimold (1511 PKG) (Pb-Free) Note	G4W	 Embossed tape 8 mm wide Pin 1, 6 face the perforation side of the tape Qty 5 kpcs/reel

Note With regards to terminal solder (the solder contains lead) plated products (conventionally plated), contact your nearby sales office.

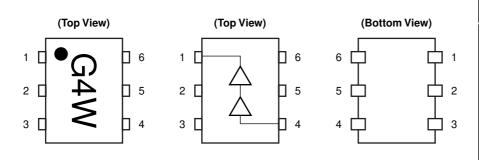
Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: μ PG2310TK-A

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	Vcc2/OUT
2	GND
3	Vcc1
4	IN
5	GND
6	GND

ABSOLUTE MAXIMUM RATINGS (Ta = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	Vcc1, Vcc2	+5.0	٧
Input Power	Pin	-10	dBm
Total Power Dissipation	Ptot	300 Note	mW
Operating Ambient Temperature	TA	-45 to +85	°C
Storage Temperature	T _{stg}	-55 to +150	°C

Note Mounted on double-sided copper-clad $50 \times 50 \times 1.6$ mm epoxy glass PWB, TA = $+85^{\circ}$ C

RECOMMENDED OPERATING RANGE

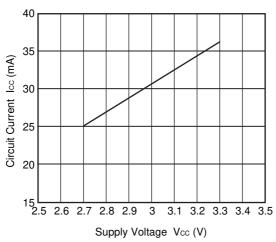
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	f _{opt}	2 320	2 340	2 360	MHz
Supply Voltage	Vcc1, Vcc2	+2.7	+3.0	+3.3	٧
Operating Ambient Temperature	Та	-45	+25	+85	°C

ELECTRICAL CHARACTERISTICS (TA = +25°C, Vcc1 = Vcc2 = +3.0 V, Zo = 50 Ω , unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Power Gain	G₽	f = 2 340 MHz, Pin = -30 dBm	25.0	27.0	-	dB
Noise Figure	NF	f = 2 340 MHz	-	1.8	2.0	dB
Input Return Loss	RLin	f = 2 340 MHz, Pin = -30 dBm	-	13	-	dB
Output Return Loss	RLout	f = 2 340 MHz, Pin = -30 dBm	-	15	-	dB
Output 3rd Order Distortion Intercept Point	OIP ₃	f1 = 2 340 MHz, f2 = 2 340.1 MHz	+26.5	+28.5	=	dBm
Circuit Current Note	lcc	f = 2 340 MHz, Pin = -30 dBm	-	30	35	mA

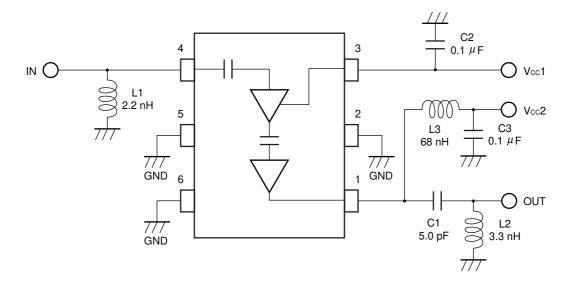
Note Please refer to following chart.





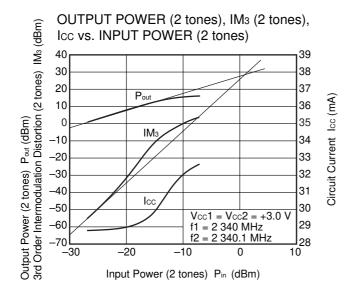
Remark The graph indicates nominal characteristics.

TEST CIRCUIT



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

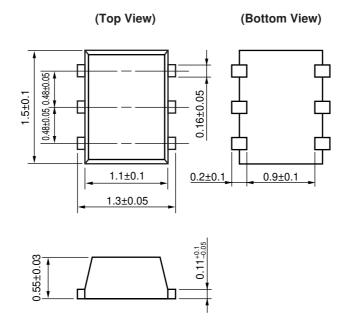
TYPICAL CHARACTERISTICS (T_A = +25°C, unless otherwise specified)



Remark The graph indicates nominal characteristics.

PACKAGE DIMENSIONS

6-PIN LEAD-LESS MINIMOLD (1511 PKG) (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).



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Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices	
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)
Mercury	< 1000 PPM	Not Detected	
Cadmium	< 100 PPM	Not Detected	
Hexavalent Chromium	< 1000 PPM	Not Detected	
PBB	< 1000 PPM	Not Detected	
PBDE	< 1000 PPM	Not Detected	

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

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In no event shall CEL's liability arising out of such information exceed the total purchase price of the CEL part(s) at issue sold by CEL to customer on an annual basis.

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